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(54) **PRINTED CIRCUIT BOARD AND FABRICATING METHOD THEREOF, AND DISPLAYING DEVICE**

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(57) **ABSTRACT**

A printed circuit board and a fabricating method thereof, and a displaying device. The printed circuit board includes a hard-board region (**30**) and a soft-board region (**31**), the soft-board region (**31**) is located at the periphery of the first edge (**30***a*) of the hard-board region (**30**), the printed circuit board within the hard-board region (**30**) includes a base plate (**301**), and an adhesive film (**302**), a covering film (**303**) and a first metal layer (**304**) that are arranged in layer configuration on one side of the base plate (**301**), the adhesive film (**302**) is closest to the base plate (**301**), a flow guiding groove (**3030**) is disposed on the surface of the side of the covering film (**303**) that is closer to the adhesive film (**302**), and the flow guiding groove (**3030**) extends to a second edge (**30***b*) of the hard-board region (**30**). By disposing the flow guiding groove on the surface of the side of the covering film that is closer to the adhesive film, and disposing that the flow guiding groove extends to the second edge of the hard-board region, the overflowing adhesive of the adhesive film can be effectively guided to flow to the periphery of the second edge via the flow guiding groove, and because the soft-board region is located at the periphery of the first edge, the method can effectively reduce the overflowing adhesive to flow to the soft-board region, reduce the reserved overflowing-adhesive room of the printed circuit board, and reduce the size of the printed circuit board.